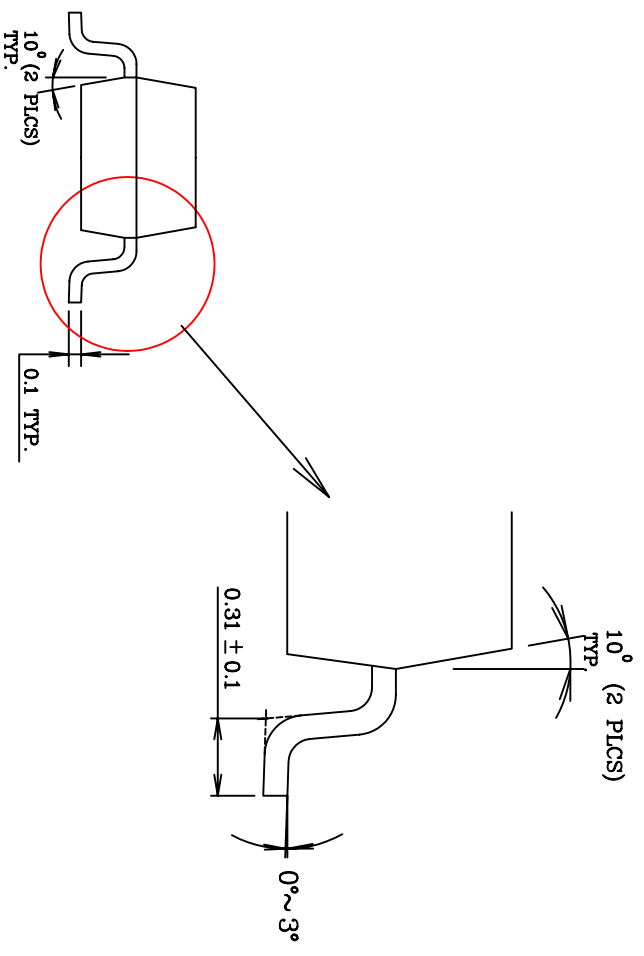
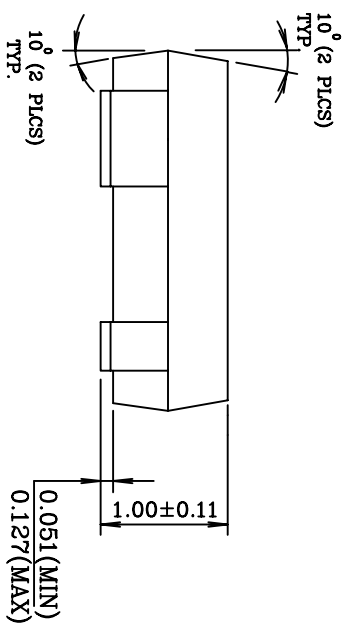
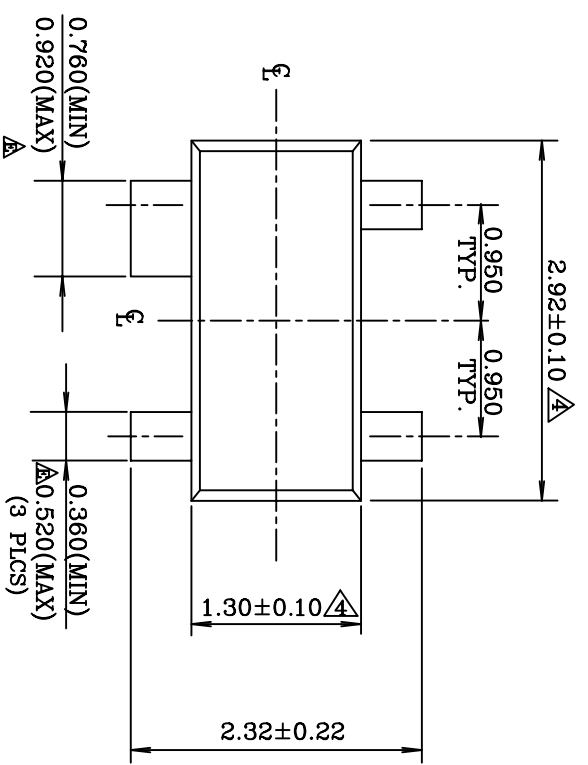


- NOTE:
1. Dimensions and tolerances are as per ANSI Y14.5M, 1982.
  2. Package surface to be mirror finish.
  3. Die is facing up for mold & trim/form.
- △ Dimensions are exclusive of mold flash and gate burr.



ALLOY FRAME

G	Note: Metal burr revise to gate burr as per Jedec spec.	18/01/02	ANDREW	PT
F	ADD NOTE NO.4.	15/01/01	ANDREW	PT
△	Change lead width to 0.360(Min)&0.520(Max) - (was 0.4) and big lead width to 0.760(Min)&0.920(Max) - (was 0.8)	03/06/99	ANDREW	PT
D	Change the stand off to follow jedec spec 0.051(min)~0.127(max) [was 0.013(min)~0.10(max)]	24/11/97	ANDREW	PT
C	Change the Lead frame thickness to 0.1mm (was 0.125mm).	04/06/97	CH TAN	PT
B	Change the Lead Spread to 2.32+/-0.22 (was 2.3+/-0.15).	29/01/97	CH TAN	PT
A	Initial Design.	06/01/95	CH TAN	PT
REV.	DESCRIPTION	DATE	BY	APPD

TOLERANCES		UNIT:	SCALE:	DWN:	ANDREW	DATE:	18/01/02
REFER TO THE SPECIFICATION ABOVE.		MM	NTS	APPD:	CH TAN	DATE:	
		SYMBOL		APPD:	CK TANG	DATE:	
				APPD:	CW CHAI	DATE:	
				APPD:	SRI	DATE:	
				DWG. NO:	SOT-P-143	REV.:	G
Reference To Jedec Spec # : T0253 Issue C							
SOT-143 PACKAGE CASE OUTLINE							
SHEET NO : 1 OF 1.							